INTEGRATED CIRCUITS

DATA SHEET

TDA9830 TV sound AM-demodulator and audio source switch

Product specification Supersedes data of March 1992 File under Integrated Circuits, IC02 June 1994

Philips Semiconductors



PHILIPS

TDA9830

FEATURES

- Adjustment free wideband synchronous AM demodulator
- Audio source-mute switch (low noise)
- Audio level according EN50049
- 5 to 8 V power supply or 12 V alternative
- Low power consumption.

GENERAL DESCRIPTION

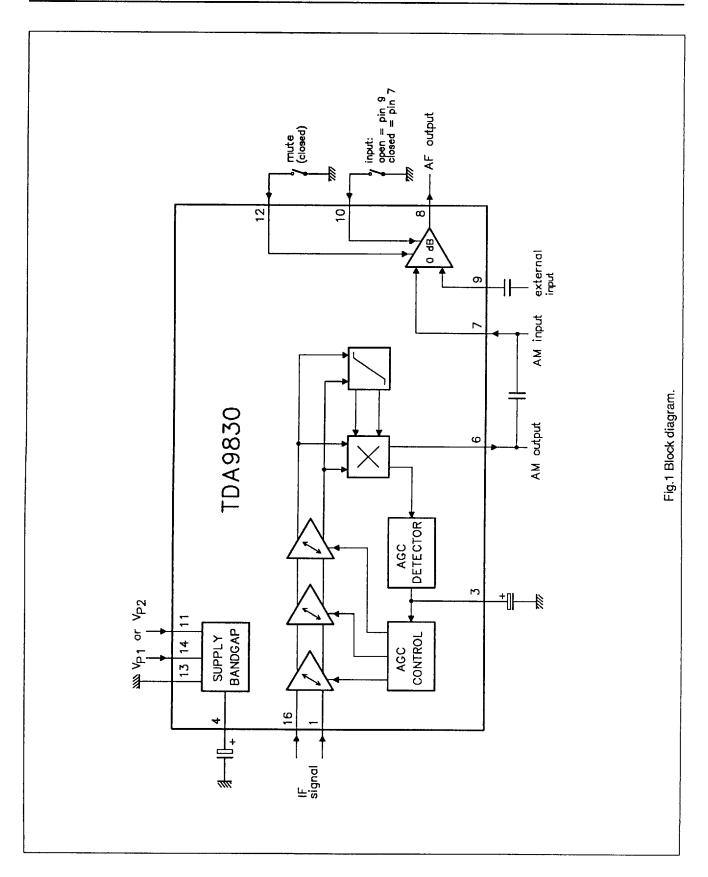
The TDA9830, a monolithic integrated circuit, is designed for AM-sound demodulation used in L- and L'-standard. The IC provides an audio source selector and also mute switch.

QUICK REFERENCE DATA

SYMBOL	PARAMETER	MIN.	TYP.	MAX.	UNIT
V ₁₄	positive supply voltage	4.5	5.0	8.8	V
V ₁₁	supply voltage (alternative)	10.8	12.0	13.2	٧
I _{14,11}	supply current	24	30	36	mA
V ₁₋₁₆	IF sensitivity (RMS value) (for -3 dB AF-signal)	-	60	100	μV
Gv	gain control	60	66	_	dB
V ₆	AF output signal (m = 54%) (RMS value)	400	500	600	mV
V ₆	S/N ratio acc. CCIR468-3 (IF-signal 10 mV _{RMS})	47	53	_	dB
V _{7,9}	AF input signal (for THD < 1.5%) (RMS value)	••••	_	1.2	V
V ₈	crosstalk and mute attenuation	80	90	_	dB
T _{amb}	operating ambient temperature	0	_	+70	°C

ORDERING INFORMATION

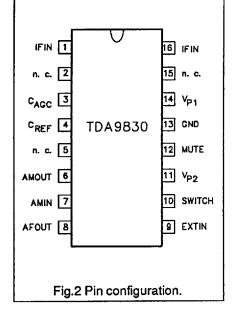
EVTENDED	PACKAGE				
EXTENDED TYPE NUMBER	PINS POSITION		MATERIAL	CODE	
TDA9830	16	DIL	plastic	SOT38GG	
TDA9830T	16	SO	plastic	SOT109	



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PINNING

SYMBOL	PIN	DESCRIPTION	
IFIN	1	sound IF differential input signal	
n.c.	2	not connected	
CAGC	3	AGC capacitor	
CREF	4	REF voltage filtering capacitor	
n.c.	5	not connected	
AMOUT	6	AM demodulator output	
AMIN	7	input signal (from AM) to audio switch	
AFOUT	8	output signal from audio switch	
EXTIN	9	input signal (from external) to audio switch	
SWITCH	10	switch input select control	
V _{p2}	11	supply voltage +12 V (alternative)	
MUTE	12	mute control	
GND	13	ground (0 V)	
V _{p1}	14	supply voltage +5 to +8 V	
n.c.	15	not connected	
IFIN	16	sound IF differential input signal	



FUNCTIONAL DESCRIPTION

Sound IF input

The sound IF amplifier consists of three AC-coupled differential amplifier stages each with approximately 20 dB gain. At the output of each stage is a multiplier for gain controlling (→ current distribution gain control). The overall control range is approximately –6 to +60 dB and the frequency response (–3 dB) of the IF amplifier is approximately 6 to 70 MHz. The steepness of gain control is approximately 10 mV/dB.

IF AGC

The automatic gain control voltage to maintain the AM demodulator output signal at a constant level is generated by a mean level detector. This AGC-detector charges and discharges the capacitor at pin 3 controlled by the output signal of the AM-demodulator compared to an internal reference voltage. The maximum charge/discharge current is approximately 5 μ A. This value in combination with the value of the

AGC capacitor and the AGC steepness determines the lower cut-off audio frequency and the THD-figure at low modulation frequency of the whole AM-demodulator. Therefore a large time constant has to be choosen which leads to slow AGC reaction at IF level change. To speed up the AGC in case of IF signal jump from low to high level, there is an additional comparator built in, which can provide additional discharge current from the AGC capacitor up to 5 mA in a case of overloading the AM demodulator by the internal IF signal.

AM-demodulator

The IF amplifier output signal is fed to a limiting amplifier (two stages) and to a multiplier circuit. However the limiter output signal (which is not any more AM modulated) is also fed to the multiplier, which provides AM demodulation (in phase demodulation). After lowpass filtering (fg ~ 400 kHz) for carrier rejection and buffering, the demodulator output signal is present

at pin 6. The AM demodulator operates over a wide frequency range, so that in combination with the frequency response of the IF amplifier applications in a frequency range from approximately 6 MHz up to 70 MHz are possible.

Audio switch

This circuit is an operational amplifier with three input stages and internal feedback network determining gain (0 dB) and frequency response (fg ≈ 700 kHz). Two of the input stages are connected to pin 7 and pin 9, the third input stage to an internal reference voltage. Controlled by the switching pins 10 and 12, one of the three input stages can be activated and a choice made between two different AF signals or mute state. The selected signal is present at pin 8. The decoupling capacitors at the input pins are needed, because the internally generated bias voltage for the input stages must not be influenced by the application in order to avoid DC-plop in case of switching.

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The AM demodulator output is designed to provide almost the same DC voltage as the input bias voltage of the audio switch. But there may be spread between both voltages. Therefore it is possible to connect pin 6 directly to pin 7 (without a decoupling capacitor), but in this event the DC-plop for switching can increase up to 100 mV.

Reference circuit

This circuit is a band gap stabilizer in combination with a voltage regulation amplifier, which provides an internal reference voltage of about 3.6 V nearly independent from supply voltage and temperature. This reference voltage is filtered by the capacitor at pin 4 in order to reduce noise. It is used as a reference to generate all important voltages and currents of the circuit.

For application in 12 V power supply concepts, there is an internal voltage divider in combination with a Darlington transistor in order to reduce the supply voltage for all IC function blocks to approximately 6 V. This is necessary because of use of modern high frequency IC technology, where most of the used integrated components are only allowed to operate at maximum 9 V supply voltage.

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC134).

SYMBOL	PARAMETER	MIN.	MAX.	UNIT
V ₁₄₋₁₃	supply voltage V _{P1}	-0.5	+8.9	٧
V ₁₁₋₁₃	supply voltage V _{P2}	-0.5	+13.3	V
V _{10,12-13}	switching voltage	-0.5	V _P + 0.5	V
T _{amb}	operating ambient temperature	0	+70	°C
T _{stg}	storage temperature	-25	+150	°C

Note to the limiting values

1. To avoid an inadmissible increase of ambient temperature, it is not allowed to short-circuit pin 11 for more than 10 seconds to ground.

THERMAL RESISTANCE

SYMBOL	PARAMETER	THERMAL RESISTANCE
R _{th j-a}	from junction to ambient in free air	
	SOT38	74 K/W
	SOT109	100 K/W

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CHARACTERISTICS

 $V_{p1} = 5.0 \text{ V}$ at pin 14; $T_{amb} = +25 \,^{\circ}\text{C}$; sound carrier fsc = 32.4 MHz modulated with f = 1 kHz and modulation depth m = 54%. IF input signal (sound carrier): $V_{1-16} = 10 \,\text{mV}_{RMS}$; unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V ₁₄₋₁₃	positive supply voltage V _{P1}	note 1	4.5	5.0	8.8	V
V ₁₁₋₁₃	positive supply voltage V _{P2}	note 1	10.8	12.0	13.2	V
111/114	current consumption		24	30	36	mA
IF amplifie	r and gain control					
R ₁₋₁₆	input resistance		1.75	2.2	2.65	kΩ
C ₁₋₁₆	input capacitance		1.0	1.5	2.2	pF
V ₁₋₁₆	minimum IF input signal (RMS value)	note 2	_	60	100	μV
V ₁₋₁₆	maximum IF input signal (RMS value)	note 3	70	120	_	mV
Gν	gain control		60	66	_	dB
l ₃	maximum AGC charging/discharging current		3.5	5	7	μΑ
l ₃	fast AGC discharging current			_	5	mA
V ₃ - V ₁₃	gain control voltage (Gmin - Gmax)		1.5	_	2.8	V
В	–3 dB IF bandwidth	upper cut-off frequency	50	70	-	MHz
		lower cut-off frequency	_	6	10	MHz
V _{1/16-13}	DC potential		_	1.7	_	٧
AM-Demod	iulator					
V ₆₋₁₃	AF output signal (RMS value)		400	500	600	mV
В	-3 dB AF bandwidth	upper cut-off frequency	100	_	_	kHz
		lower cut-off frequency; note 7	_	_	20	Hz
V ₆₋₁₃	THD		_	0.8	2	%
V ₆₋₁₃	S/N (weighted acc. CCIR 468-3)		47	53	_	dB
V ₆₋₁₃	DC potential		2.00	2.15	2.30	٧
R ₆	output resistance (emitter follower with 0.5 mA bias current)		-	300	-	Ω
l _{6abs}	allowable AC output current		_	-	0.3	mA
16	allowable DC output current			-	-0.5	mA
Audio-swit	ich					
V7,9-13	AF-input-signal for THD < 1.5% (RMS value)		_	_	1.2	٧
V ₈₋₁₃	S/N ratio of audio switch (in accordance with CCIR 468-3)	reference signal at pin 7/9 is 0.5 V _{RMS}	70	80		dB
В	-3 dB AF bandwidth	upper limit	100	_	-	kHz
V ₈₋₁₃	THD at 1 V _{RMS} input signal at pin 7 or 9		-	0.1	1.0	%
V8-13	crosstalk and mute attenuation	20 Hz to 20 kHz	80	90	_	dB
V7,8,9-13	DC-potential		2.00	2.15	2.30	٧
R _{7,9-13}	input resistance		40	50	60	kΩ

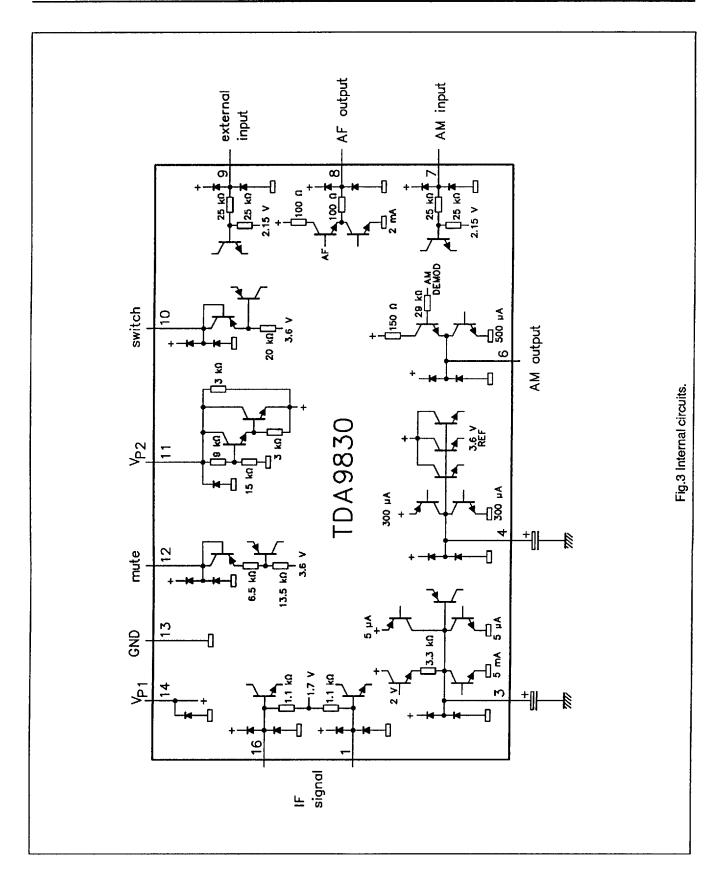
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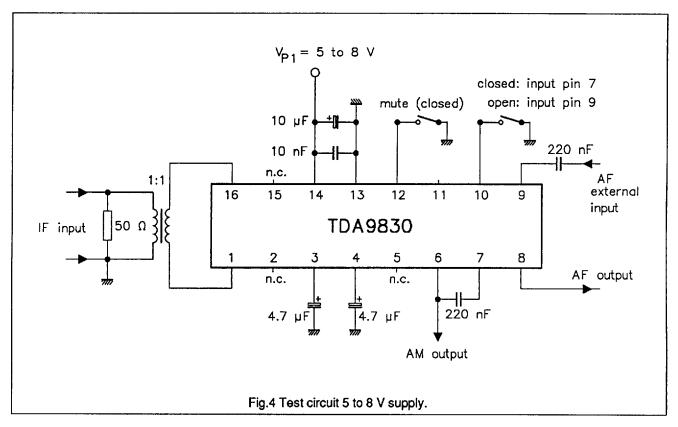
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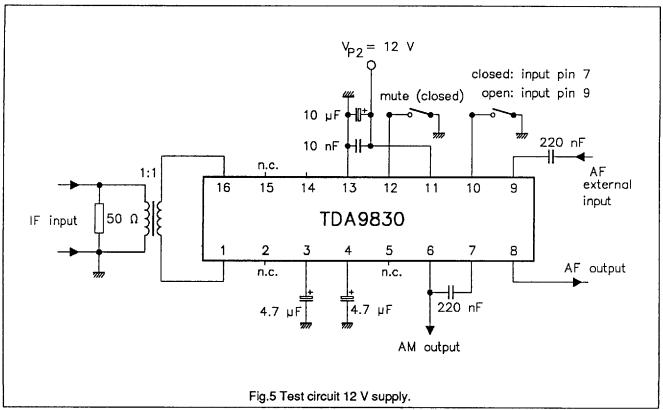
SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
G7,9-8	gain of audio switch		-0.5	0	+0.5	dB
V ₁₀₋₁₃	audio switching voltage to activate pin 7		0	-	0.8	٧
V ₁₀₋₁₃	audio switching voltage to activate pin 9	note 4	1.5	-	Vp	V
V ₁₂₋₁₃	input voltage for MUTE-ON		0	1-	0.8	٧
	input voltage for MUTE-OFF	note 4	1.5	-	VP	V
l _{10,12}	output current of switching-pins at V _{10,12-13} = 0 V		-110	-145	-185	μА
V ₈₋₁₃	DC-plop at AF output pin with switching from internal to external audio signal or to mute-state or vice-versa	note 5	-	5	10	mV
R ₈	output resistance		70	100	150	Ω
Ripple reje	ection note 6			·····		
RR	AF signal output: αRR = V _{ripple} on V _P / V _{ripple} on V _{out}		26	30	-	dB
	AF signal output with AF signal from external source		40	44	-	dB

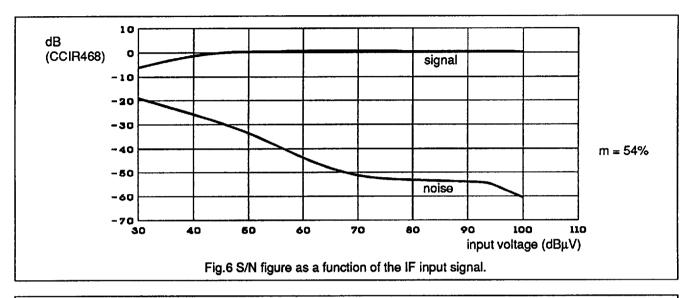
Notes to the characteristics

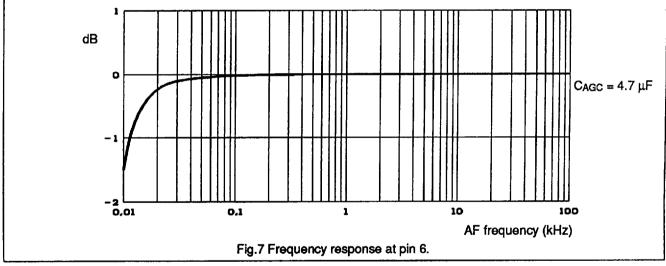
- 1. In the power supply voltage range $V_{P1} = 5.0 \text{ V}$ up to 8.0 V the performance will not change essentially. With power supply from $V_{P2} = 12.0 \text{ V}$ the performance will be comparable with the performance at $V_{P1} = 5.0 \text{ V}$ up to 8.0 V.
 - The unused power supply pin must be not connected.
- 2. Start of gain control (low IF input signal) at -3 dB AF signal reduction at pin 6.
- 3. End of gain control (high IF input signal) at +1 dB AF signal expansion at pin 6.
- 4. This state is also valid for pin left open-circuit.
- 5. If a DC-plop of about maximum 100 mV is acceptable when switching from internal to external audio-signal or from internal to mute state or vice-versa, the capacitor between pin 6 and 7 can be omitted and pin 6 can be connected to pin 7.
- 6. Measured with Vripple = 200 mV(p-p) at 70 Hz superimposed on supply voltage Vp.
- 7. Dependent on value of AGC capacitor.

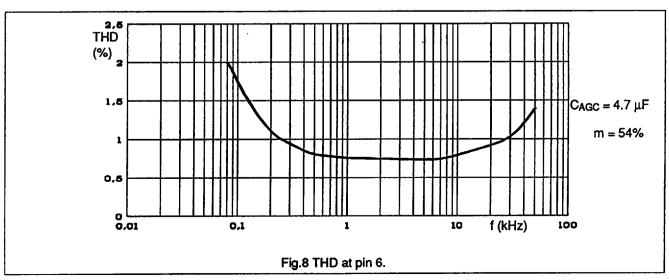


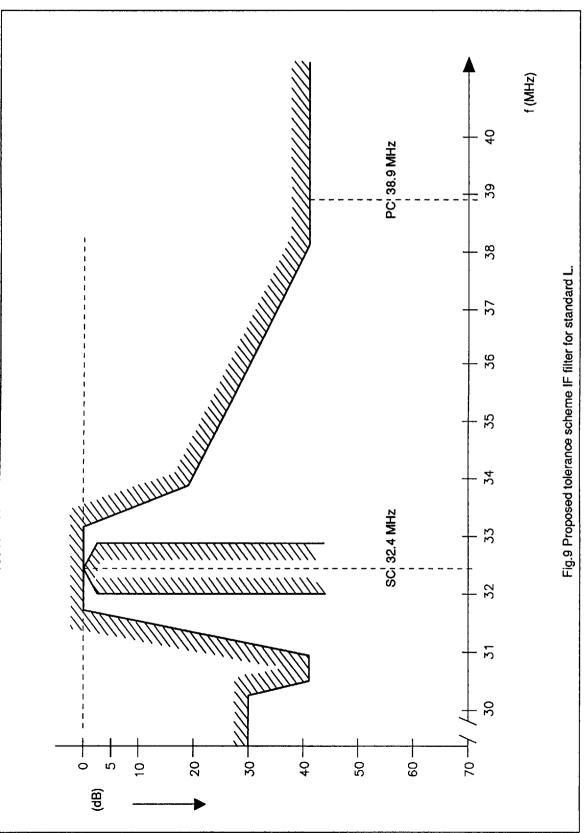








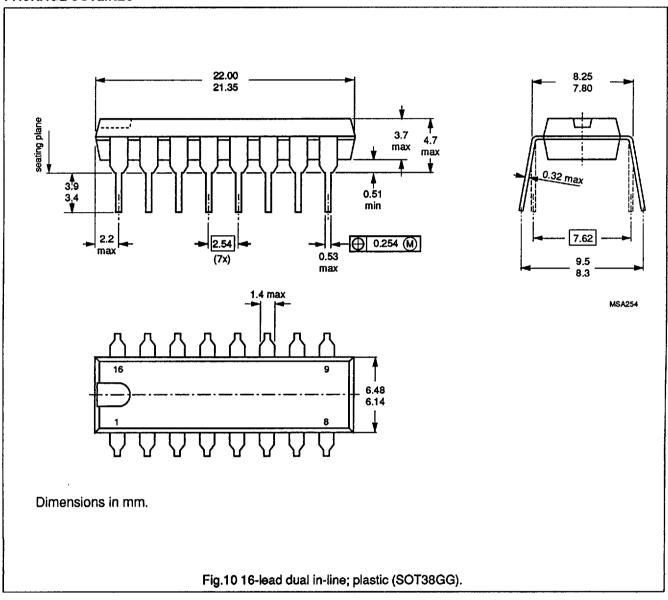


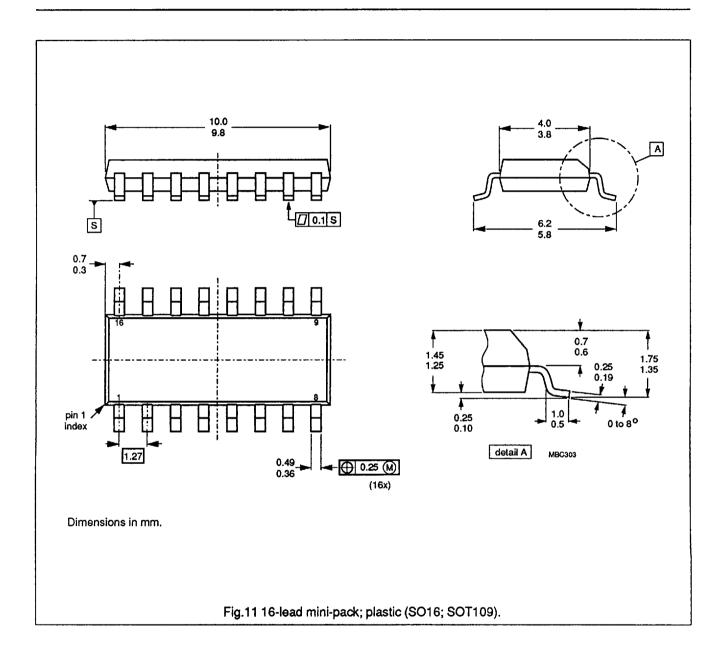


With an IF filter according to this proposal, the video buzz suppression on the audio output is better than 50 dB (in accordance with CCIR468-3, m = 54%) for the worst case video modulation with 6 kHz sinewave black-to-white.

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PACKAGE OUTLINES





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SOLDERING

Plastic dual in-line packages

BY DIP OR WAVE

The maximum permissible temperature of the solder is 260 °C; this temperature must not be in contact with the joint for more than 5 s. The total contact time of successive solder waves must not exceed 5 s.

The device may be mounted up to the seating plane, but the temperature of the plastic body must not exceed the specified storage maximum. If the printed-circuit board has been preheated, forced cooling may be necessary immediately after soldering to keep the temperature within the permissible limit.

REPAIRING SOLDERED JOINTS

Apply the soldering iron below the seating plane (or not more than 2 mm above it). If its temperature is below 300 °C it must not be in contact for more than 10 s; if between 300 and 400 °C, for not more than 5 s.

Plastic mini-packs

BY WAVE

During placement and before soldering, the component must be fixed with a droplet of adhesive. After curing the adhesive, the component can be soldered. The adhesive can be applied by screen printing, pin transfer or syringe dispensing.

Maximum permissible solder temperature is 260 °C and maximum duration of package immersion in solder bath is 10 s, if allowed to cool to less than 150 °C within 6 s. Typical dwell time is 4 s at 250 °C.

A modified wave soldering technique is recommended using two solder waves (dual-wave) in which a turbulent wave with high upward pressure is followed by a smooth laminar wave. Using a mildly-activated flux eliminates the need for removal of corrosive residues in most applications.

By solder paste reflow

Reflow soldering requires the solder paste (a suspension of fine solder particles, flux and binding agent) to be applied to the substrate by screen printing, stencilling or pressure-syringe dispensing before device placement.

Several techniques exist for reflowing; for example, thermal conduction by heated belt, infrared, and vapour-phase reflow. Dwell times vary between 50 and 300 s according to method. Typical reflow temperatures range from 215 to 250 °C.

Preheating is necessary to dry the paste and evaporate the binding agent. Preheating duration: 45 min at 45 °C.

REPAIRING SOLDERED JOINTS
(BY HAND-HELD SOLDERING IRON OR PULSE-HEATED SOLDER TOOL)

Fix the component by first soldering two, diagonally opposite, end pins. Apply the heating tool to the flat part of the pin only. Contact time must be limited to 10 s at up to 300 °C. When using proper tools, all other pins can be soldered in one operation within 2 to 5 s at between 270 and 320 °C. (Pulse-heated soldering is not recommended for SO packages).

For pulse-heated solder tool (resistance) soldering of VSO packages, solder is applied to the substrate by dipping or by an extra thick tin/lead plating before package placement.

Philips Semiconductors Product specification

TV sound AM-demodulator and audio source switch

TDA9830

DEFINITIONS

Data sheet status				
Objective specification This data sheet contains target or goal specifications for product development.				
Preliminary specification	This data sheet contains preliminary data; supplementary data may be published later.			
Product specification	This data sheet contains final product specifications.			
Limiting values				
more of the limiting values operation of the device at	in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or is may cause permanent damage to the device. These are stress ratings only and these or at any other conditions above those given in the Characteristics sections of this d. Exposure to limiting values for extended periods may affect device reliability.			
Application information				
Where application information	ation is given, it is advisory and does not form part of the specification.			

LIFE SUPPORT APPLICATIONS

These products are not designed for use in life support appliances, devices, or systems where malfunction of these products can reasonably be expected to result in personal injury. Philips customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify Philips for any damages resulting from such improper use or sale.

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